



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

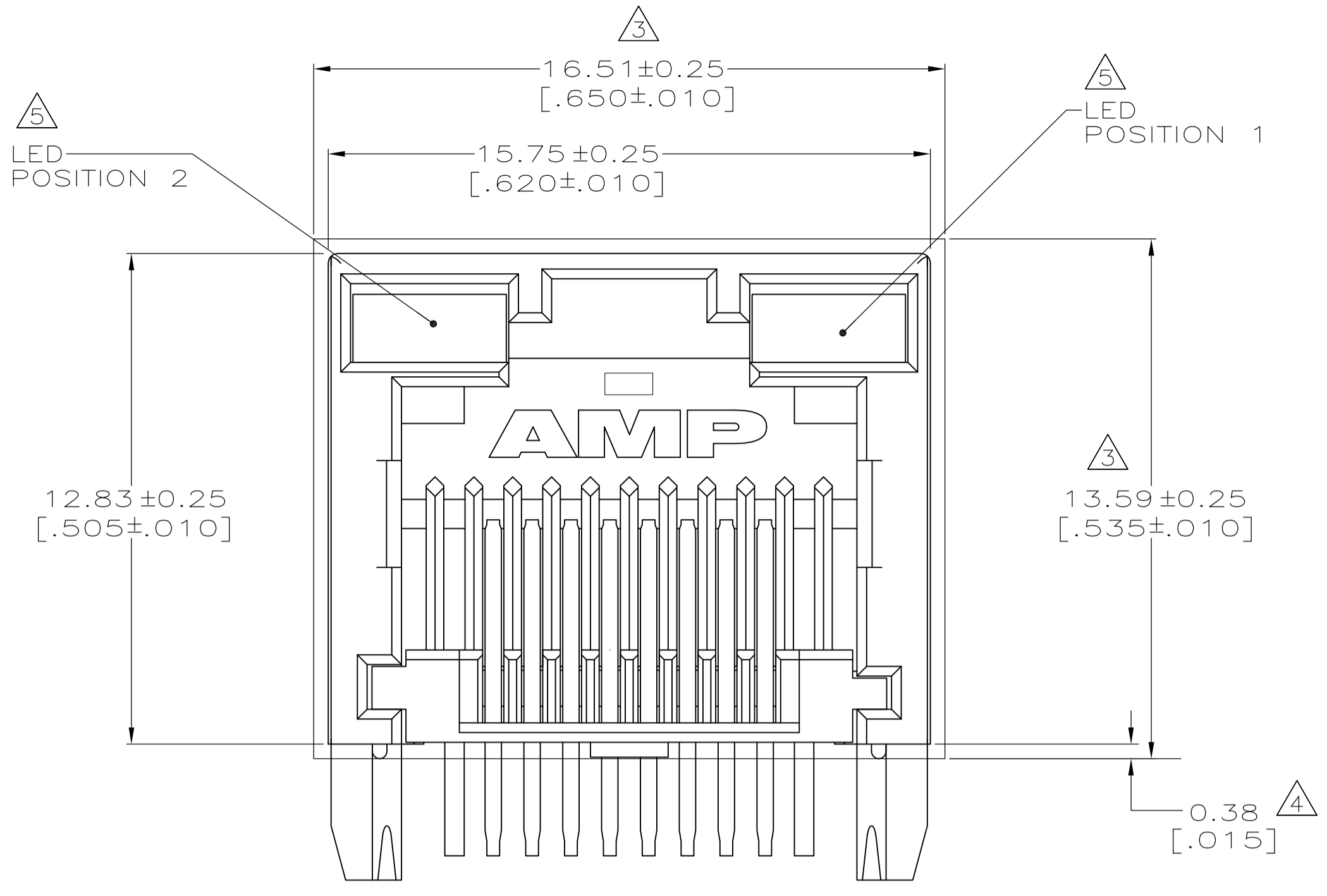
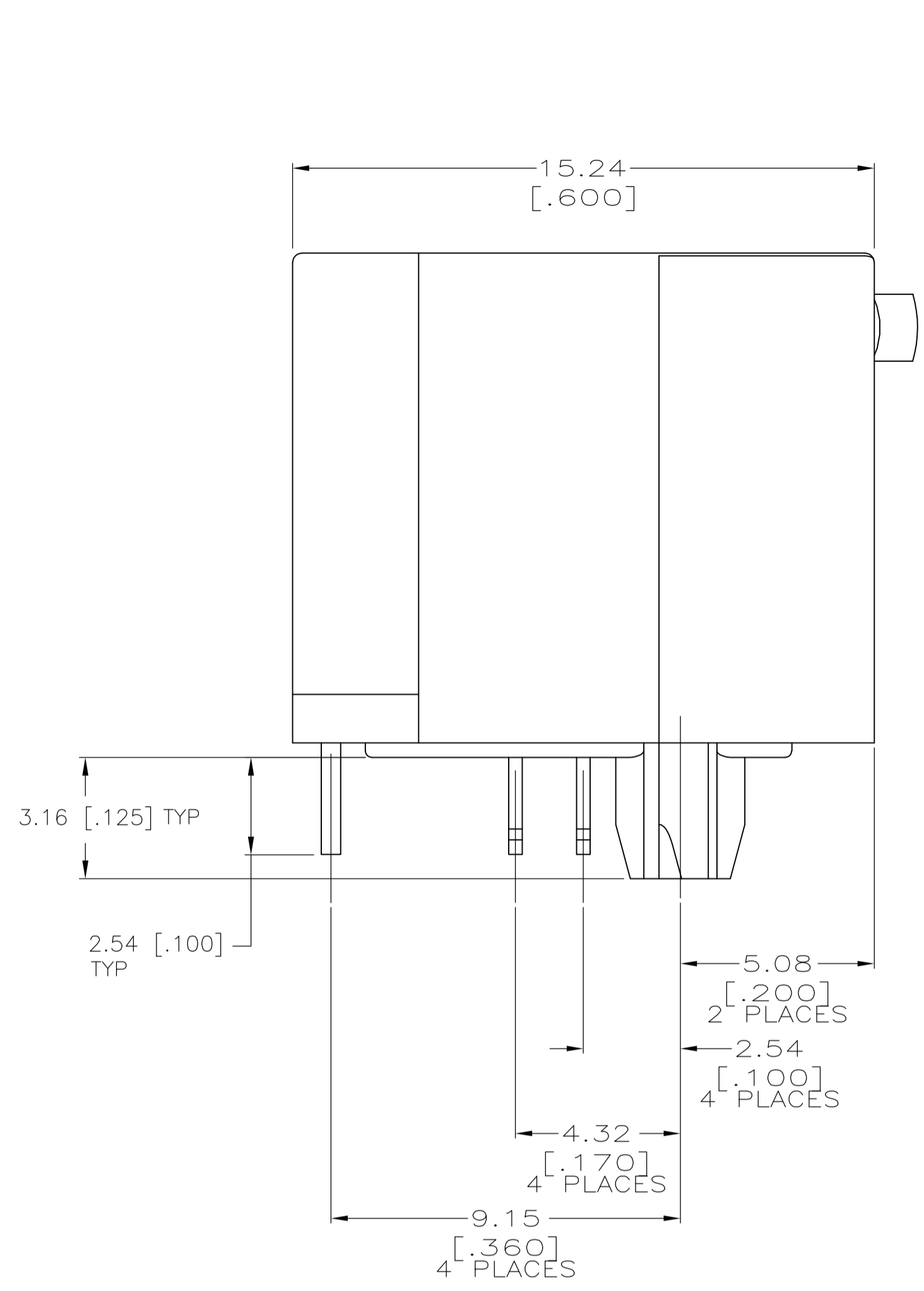
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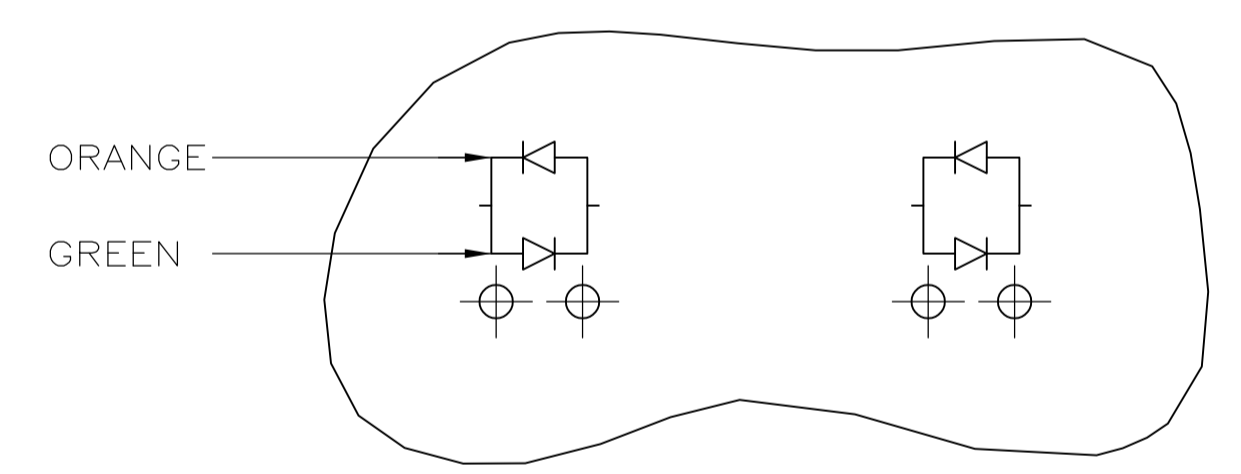
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



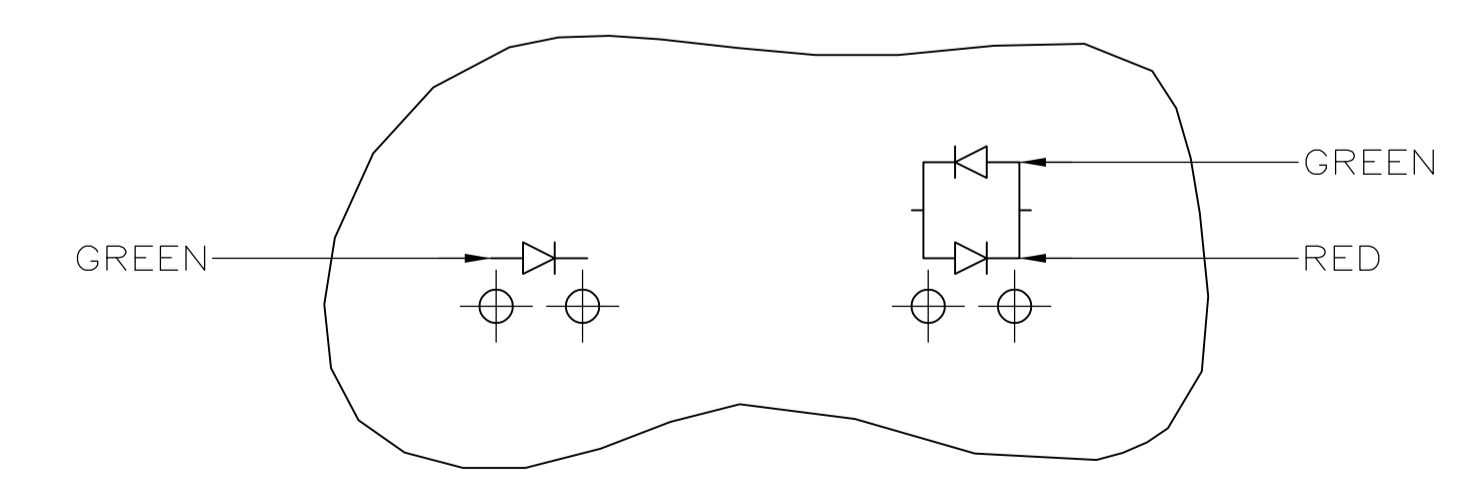
LOC		DIST		REVISIONS			
AA	22	REV	DATE	BY	CHK	APPV	
C2	REVISED PER ECO-11-005033		25MAR11	RK	HMR		



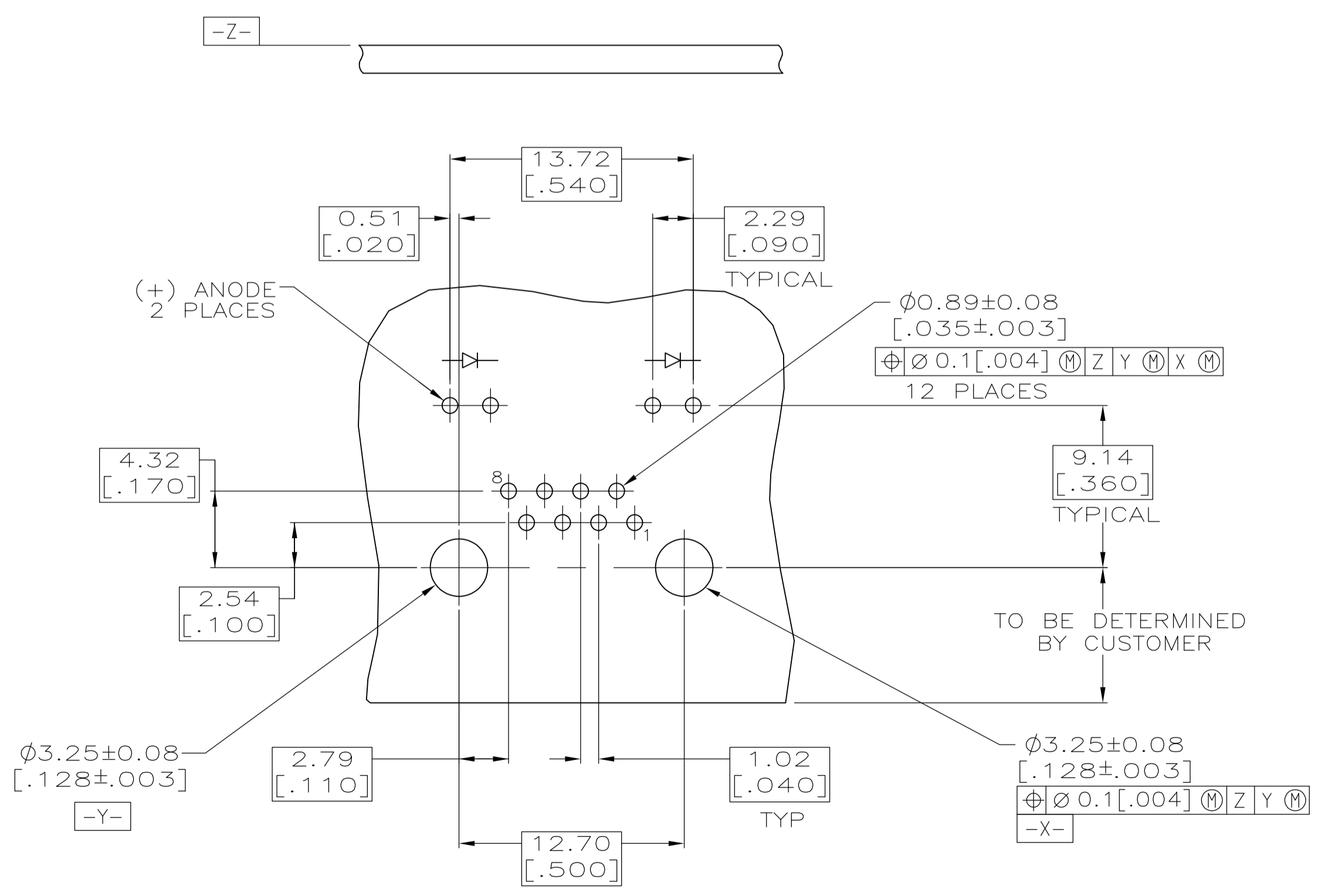
- MATERIAL:**
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27µm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [.000050] MINIMUM THICK NICKEL.
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 µm[.0003500] THICK Sn/Cu OVER 2.03 µm[.000080] THICK Ag OVER 1.02µm[.000040] THICK Cu OVER 3.56 µm[.000140] THICK Ni OVER 1.02µm[.000040] Cu UNDERPLATE
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
 - SUGGESTED PANEL OPENING DIMENSIONS.
 - SUGGESTED CLEARANCE BETWEEN BOTTOM OF CONNECTOR AND BOTTOM PANEL OPENING.
 - SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
 - THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
 - OBsolete PARTS: OBsolete CIS STREAMLINING PER D.RENAUD/D.SINISI



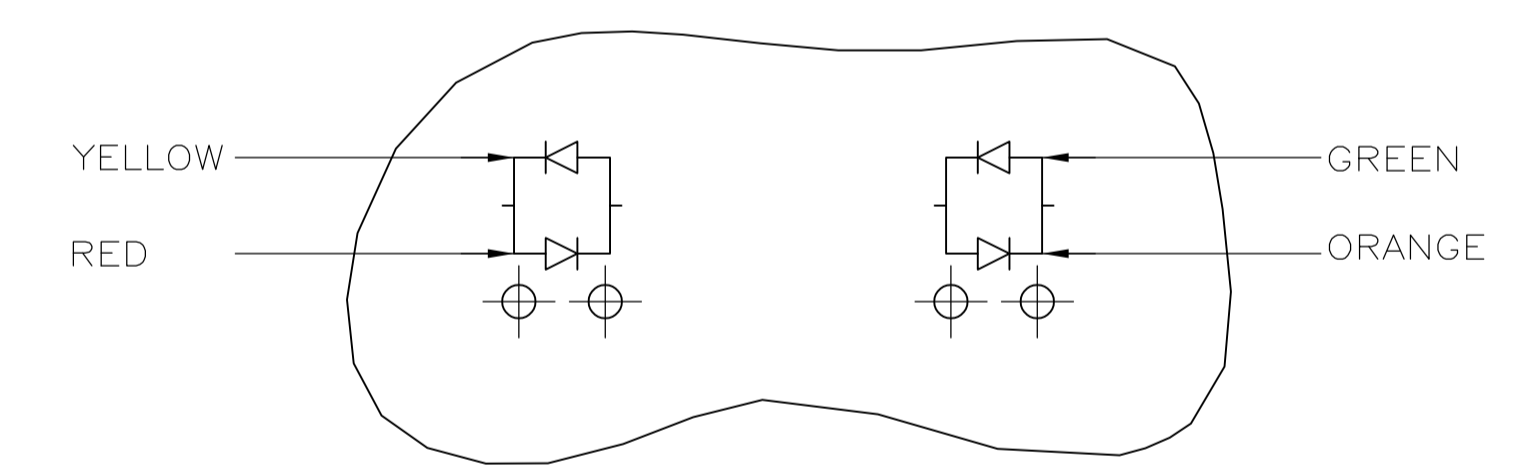
LED CURRENT DIAGRAM
5406533-7 ONLY



LED CURRENT DIAGRAM
1-5406533-0 PART ONLY



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)



LED CURRENT DIAGRAM
1-5406533-8 ONLY

OBsolete	TRAY	RED/YELLOW	ORANGE/GREEN	1-5406533-8
	TRAY	GREEN	-	1-5406533-7
	TRAY	GREEN	RED/GREEN	1-5406533-7
	TRAY	ORANGE/GREEN	ORANGE/GREEN	5406533-7
OBsolete	TRAY	YELLOW	YELLOW	5406533-6
	TRAY	GREEN	GREEN	5406533-5
OBsolete	TRAY	YELLOW	-	5406533-3
	TRAY	-	GREEN	5406533-2
	TRAY	YELLOW	GREEN	5406533-1
PACKAGING		POSITION 2	POSITION 1	PART NUMBER
		INDICATOR COLOR		

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN J. ALCORTA - 13JUN2005		TE Connectivity	
DIMENSIONS: mm[INCHES]		CHK J. WESTMAN		NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S. FLICKINGER		108-1163-4	
0 PLC ± -	1 PLC ± -	PRODUCT SPEC		114-2154	
2 PLC ± 0.25[.010]	3 PLC ± 0.13[.005]	APPLICATION SPEC		SIZE CASE CODE DRAWING NO	
4 PLC ± -	ANGLES ± -	WEIGHT		RESTRICTED TO	
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	CUSTOMER DRAWING		SCALE 8:1 SHEET 1 OF 1 REV C2	